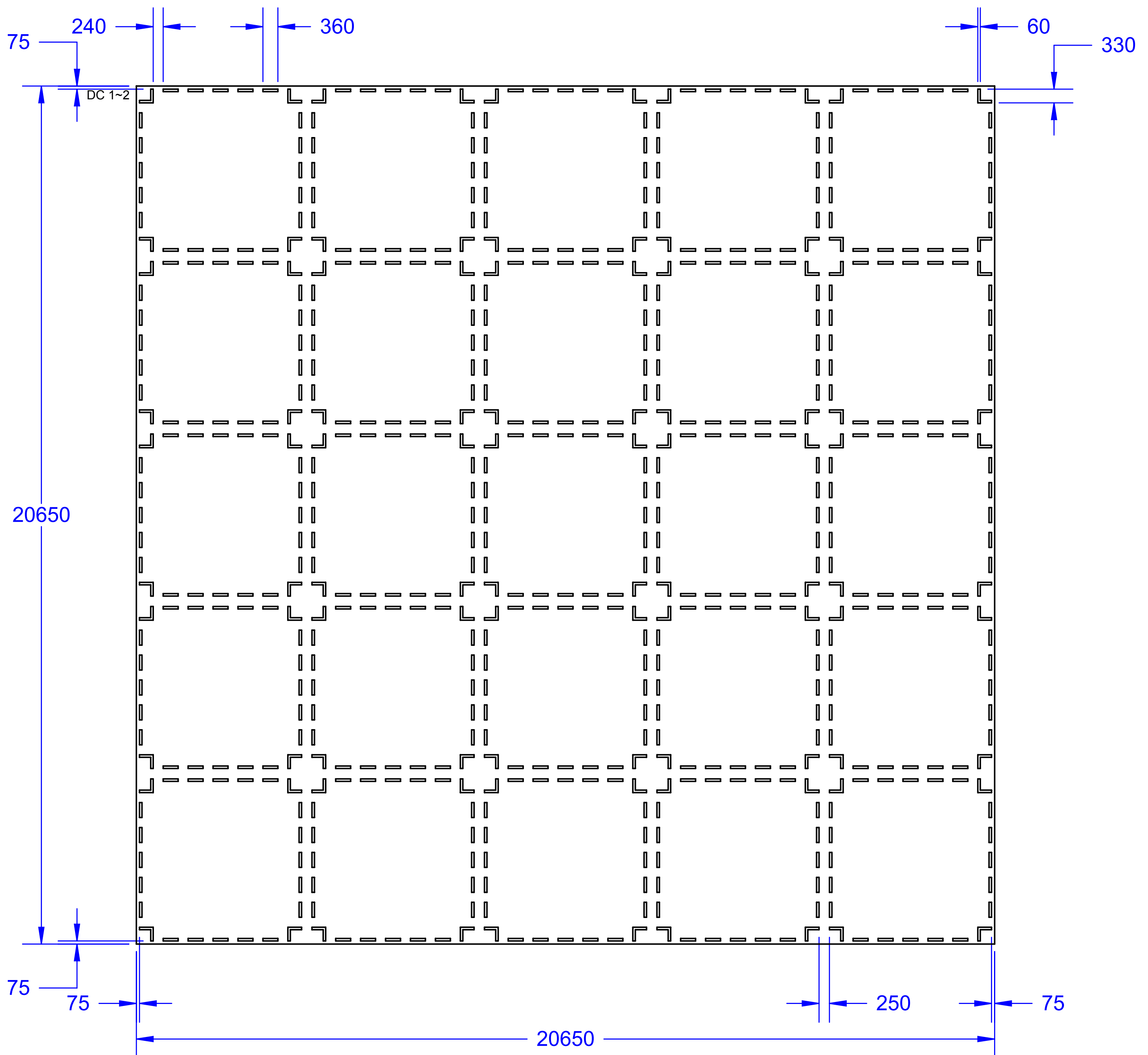
DAISY CHAIN TEST DIE
WIRE BONDABLE
SHOWN WITH CENTER PADS



Notes: (Unless Otherwise Specified)
1. DIE MATERIAL IS SILICON.
2. DIE THICKNESS 250µm ~ 725µm.
3. METALLIZATION 1.0µm ALUMINUM (Al).
4. DIE IS WITHOUT PASSIVATION.
5. WIRE BONDABLE WITH GOLD (Au) WIRE.
6. DAISY CHAIN PAIRS.

APPROVALS		DATE	TopLine®			
DRAWN	T.Au	04/15/14				
ENG	M. Hart	04/15/14	TITLE	DAISY CHAIN TEST DIE TD136 21 x 21MM		
MFG						
QA			SCALE 7:1	SIZE A	DRAWING NO. 154136	REV A
CUST						
REVISED			DO NOT SCALE DRAWING		SHEET 1 OF 2	

PERIMETER PAD TEST DIE
DAISY CHAIN
SHOWN WITHOUT CENTER PADS FOR CLARITY

SCALE 1.75:1

Notes: (Unless Otherwise Specified)
1. DIE MATERIAL IS SILICON.
2. DIE THICKNESS 250µm ~ 725µm.
3. METALLIZATION 1.0µm ALUMINUM (Al).
4. DIE IS WITHOUT PASSIVATION.
5. WIRE BONDABLE WITH GOLD (Au) WIRE.
6. DAISY CHAIN PAIRS.

DIMENSION IN MICRONS
1.0mm = 1000µm

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MFG						
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CUST						
REVISED			DO NOT SCALE DRAWING		SHEET 2 OF 2	